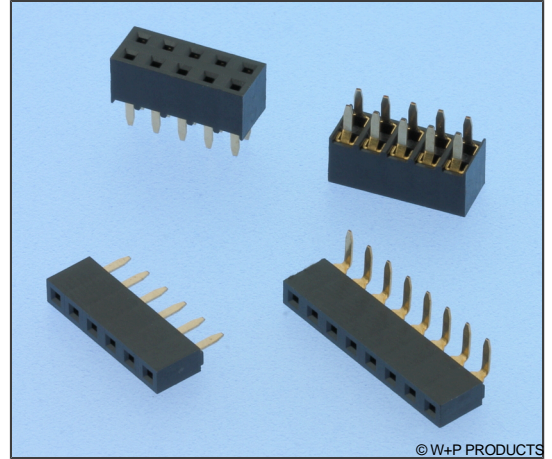


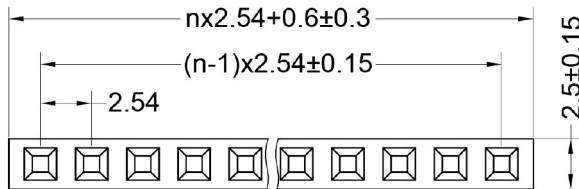
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Au über Ni <i>Au over Ni</i>
RoHS-Ausnahmen 6a-I / 6c <i>RoHS Exemptions 6a-I / 6c</i>	keine <i>none</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ <i>< 20 mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ <i>> 1000 MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	1000 V AC <i>1000 V AC</i>
Nennstrom <i>Current Rating</i>	3 A <i>3 A</i>
Temperaturbereich <i>Temperature Range</i>	-40 °C ~ +105 °C <i>-40 °C ~ +105 °C</i>
Verarbeitung <i>Processing</i>	260 °C für 10 sec. / 230 °C für 30-60 sec. <i>260 °C for 10 sec. / 230 °C for 30-60 sec.</i>

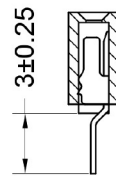
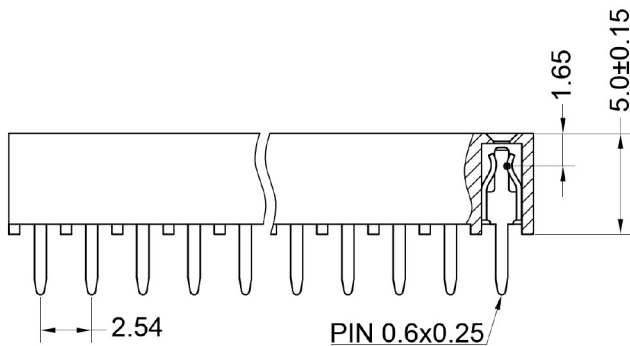
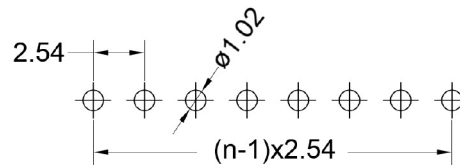


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Geeignet für 0,635mm Vierkantstifte
Mates with 0.635mm square pins



Recommended PCB Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)



Series

46-342

Contacts*

08

02-40 Einreihig
Single row

Type

1

1 Einreihig, gerade
Single row, straight

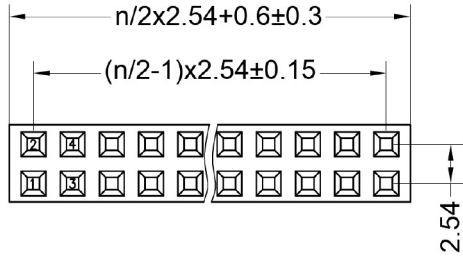
Plating

00

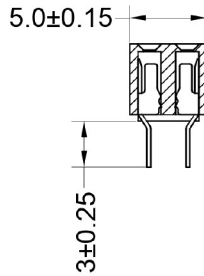
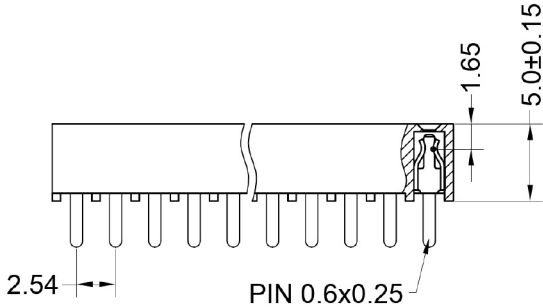
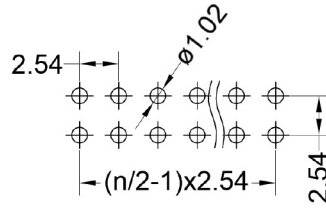
00 Vergoldet
Gold plated

46-342

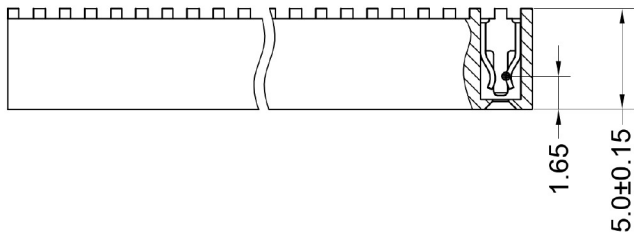
Buchsenleisten RM 2,54mm - BH 5mm
Female Headers, 2.54mm Pitch - 5mm Profile



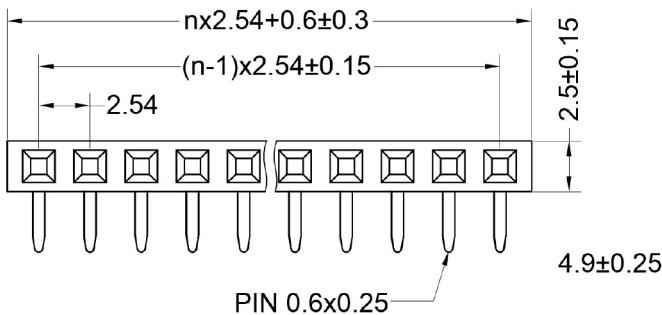
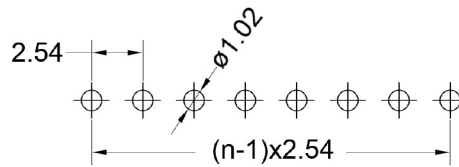
Recommended PCB Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)



Series	Contacts *	Type	Plating
46-342	12 04-60 Zweireihig Double row	2 2 Zweireihig, gerade Double row, straight	00 00 Vergoldet Gold plated



Recommended PCB Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)



Series	Contacts *	Type	Plating
46-342	10 02-40 Einreihig Single row	3 3 Einreihig, gewinkelt Single row, right-angled	00 00 Vergoldet Gold plated

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

